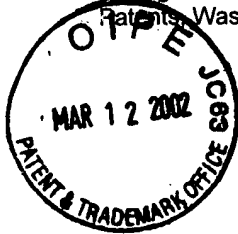


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PATENT

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Box Non-fee Amendment, Assistant Commissioner for Patents, Washington, D. C. 20231 on March 5, 2002.

*Libby G. Waits*  
Libby G. Waits



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Devine et al

Docket No. : PRS 075

Serial No. : 09/681,894

Art Unit : 2823

Filed : 6/21/2001

Examiner : Collins, D. M.

For : Radiation Hardened Microcircuits

**AMENDMENT RESPONSIVE TO THE FIRST OFFICE ACTION**

Assistant Commissioner for Patents  
Washington, D.C. 20231

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Sir:

In response to the first Office action mailed 12/10/2001, and having a shortened statutory response period that extends through and including 3/10/2002, kindly amend the claims in the following manner and consider the subsequent remarks:

In the Claims:

*sub B1*  
11. (amended) A radiation hardened silicon-based semiconductor microcircuit prepared by a process comprising the steps of:  
fabricating the microcircuit using standard techniques of silicon-based microelectronics up to the step of heating the microcircuit;  
heating the microcircuit in a vacuum; and  
annealing the microcircuit with deuterium-containing forming gas.

*A2*  
13. (new) The radiation hardened semiconductor microcircuit of Claim 12 wherein the process includes annealing the microcircuit in a vacuum.